

Lonten N-channel 600V, 1.9A, 2.5Ω LonFET™ Power MOSFET

Description

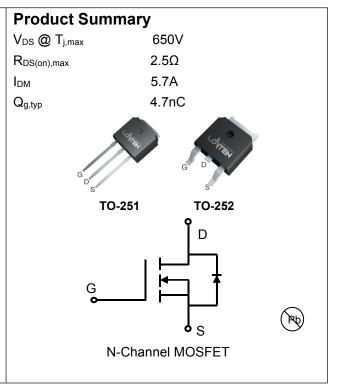
LonFETTM Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

- ♦ Ultra low R_{DS(on)}
- ◆ Ultra low gate charge (typ. Qg = 4.7nC)
- ◆ 100% UIS tested
- RoHS compliant

Applications

- Power faction correction (PFC).
- Switched mode power supplies (SMPS).
- Uninterruptible power supply (UPS).



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	600	V
Continuous drain current (T _C = 25°C)	ID	1.9	A
(T _C = 100°C)		1.2	A
Pulsed drain current 1)	I _{DM}	5.7	Α
Gate-Source voltage	V _{GSS}	±30	V
Avalanche energy, single pulse 2)	E _{AS}	30	mJ
Avalanche energy, repetitive 3)	E _{AR}	0.1	mJ
Avalanche current, repetitive 3)	I _{AR}	1.9	A
Power Dissipation TO-252/ TO-251 (Tc = 25°C)	P _D	18	W
- Derate above 25°C		0.15	W/°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C
Continuous diode forward current	Is	1.9	Α
Diode pulse current	I _{S,pulse}	5.7	Α

Thermal Characteristics TO-252

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R ₀ JC	6.7	°C/W
Thermal Resistance, Junction-to-Ambient	R _{0JA}	102	°C/W
Soldering temperature, wavesoldering only allowed	T	260	°C
at leads. (1.6mm from case for 10s)	I sold	200	



Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Reel
LSH60R2K5HT	TO-251	LSH60R2K5HT	72	
LSG60R2K5HT	TO-252	LSG60R2K5HT		2500

Electrical Characteristics T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						'
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =0.25 mA	600	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =0.25mA	2.5	3.5	4.5	V
Drain cut-off current	I _{DSS}	V _{DS} =600 V, V _{GS} =0 V,				μA
		T _j = 25°C	-	-	1	
		T _j = 125°C	-	10	-	
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =0.95 A	-			
		T _j = 25°C	-	2.2	2.5	Ω
		T _j = 150°C	-	5.6	-	
Gate resistance	R _G	f=1 MHz, open drain	-	9	-	Ω
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 100 V, V _{GS} = 0 V,	-	114	-	
Output capacitance	Coss	f = 250 kHz	-	6.1	-	pF
Reverse transfer capacitance	C _{rss}		-	0.76	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 300V, I _D = 0.95A	-	11.8	-	
Rise time	t _r	$R_G = 10\Omega$, $V_{GS}=10V$	-	30	-	ns
Turn-off delay time	t _{d(off)}	1	-	38.8	-	
Fall time	t _f		-	65.4	-	
Gate charge characteristics						•
Gate to source charge	Q _{gs}	V _{DD} =480 V, I _D =0.95A,	-	1.5	-	
Gate to drain charge	Q _{gd}	V _{GS} =0 to 10 V	-	2.0	-	nC
Gate charge total	Qg		-	4.7	-	
Gate plateau voltage	V _{plateau}	lateau		5.5	-	V
Reverse diode characteristics	.			•	•	•
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =0.95A	-	1.1	-	V
Reverse recovery time	t _{rr}	V _R =400 V, I _F =1.9A,	-	190	-	ns
Reverse recovery charge	Qrr	dI _F /dt=100 A/µs	-	1.2	-	μC
Peak reverse recovery current	Irm		-	6.2	-	Α

Notes

- 1. Limited by maximum junction temperature, maximum duty cycle is 0.75.
- 2. I_{AS} = 2A, V_{DD} = 60V, Starting T_j = 25°C.
- 3. Repetitive Rating: Pulse width limited by maximum junction temperature.



Electrical Characteristics Diagrams

Figure 1. On-Region Characteristics

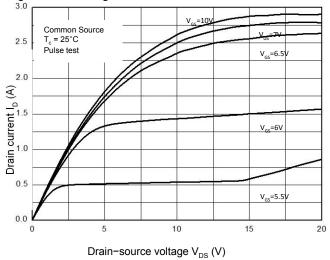


Figure 2. Transfer Characteristics

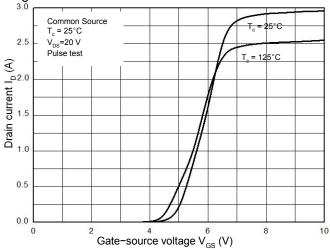


Figure 3. On-Resistance Variation vs. Drain Current

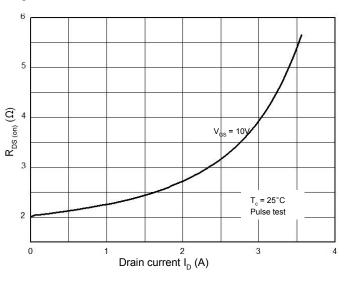


Figure 4. Threshold Voltage vs. Temperature

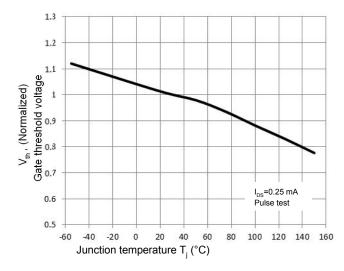


Figure 5. Breakdown Voltage vs. Temperature

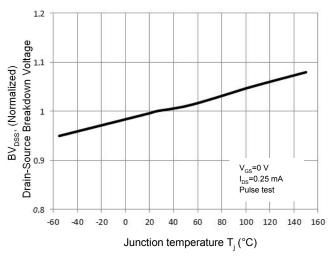


Figure 6. On-Resistance vs. Temperature

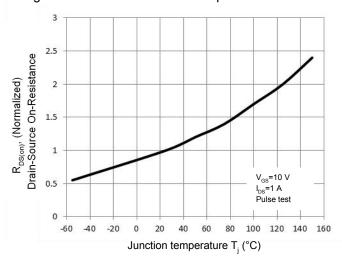
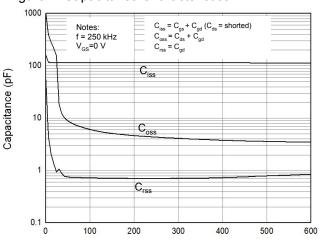


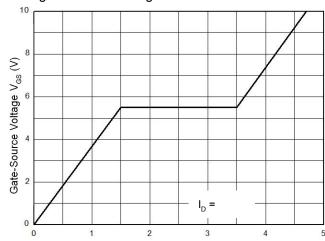


Figure 7. Capacitance Characteristics



Drain-Source Voltage V_{DS} (V)

Figure 8. Gate Charge Characterist



Total Gate Charge Q_G (nC)

Figure 9. Maximum Safe Operating Area

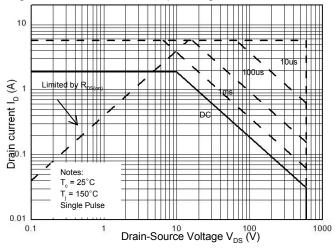
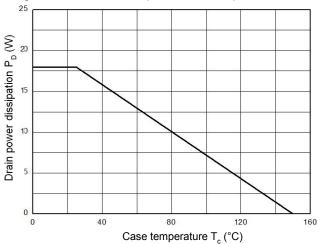
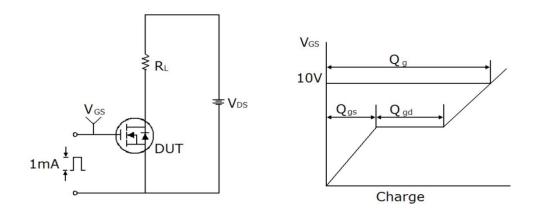


Figure 10. Power Dissipation vs. Temperature

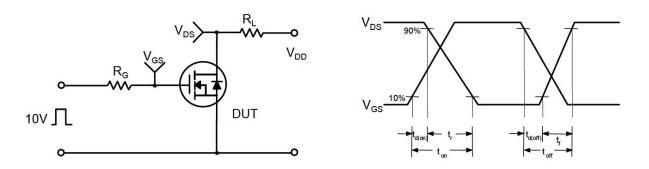




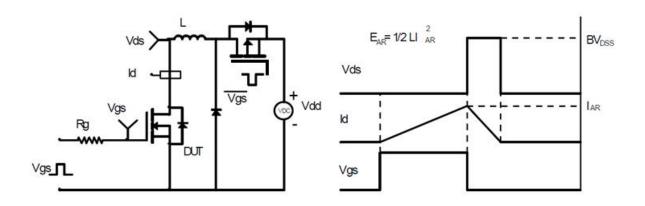
Gate Charge Test Circuit & Waveform



Switching Test Circuit & Waveforms

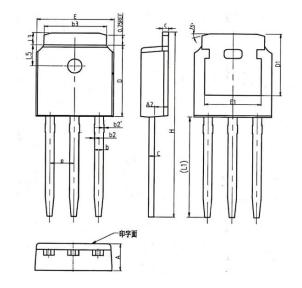


Unclamped Inductive Switching Test Circuit & Waveforms



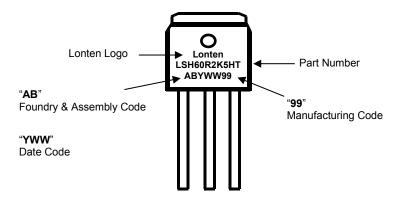


Mechanical Dimensions for TO-251



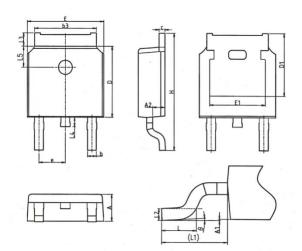
COMMON DIMENSIONS				
SYMBOL	MM			
	MIN	NOM	MAX	
А	2.20	2.30	2.38	
A2	0.97	1.07	1.17	
b	0.68	0.78	0.90	
b2	0.00	0.04	0.10	
b2'	0.00	0.04	0.10	
b3	5.20	5.33	5.46	
С	0.43	0.53	0.61	
D	5.98	6.10	6.22	
D1	5.30REF			
E	6.40	6.60	6.73	
E1	4.63	_	_	
е	2.286BSC			
Н	16.22	16.52	16.82	
L1	9.15	9.40	9.65	
L3	0.88	1.02	1.28	
L5	1.65	1.80	1.95	

TO-251 Part Marking Information



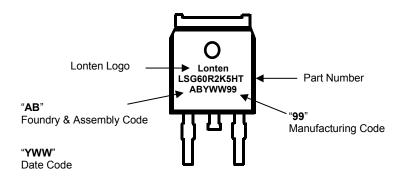


Mechanical Dimensions for TO-252



COMMON DIMENSIONS				
SYMBOL	mm			
OTWIDOL	MIN	NOM	MAX	
Α	2.20	2.30	2.38	
A1	0.00	_	0.20	
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D	5.98	6.10	6.22	
D1	5.30REF			
Е	6.40	6.60	6.73	
E1	4.63	-	_	
е	2.286BSC			
н	9.40	10.10	10.50	
L	1.38	1.50	1.75	
L1	2.90REF			
L2	0.51BSC			
L3	0.88	_	1.28	
L4	0.50	_	1.00	
L5	1.65	1.80	1.95	
θ	0°	_	8°	

TO-252 Part Marking Information





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